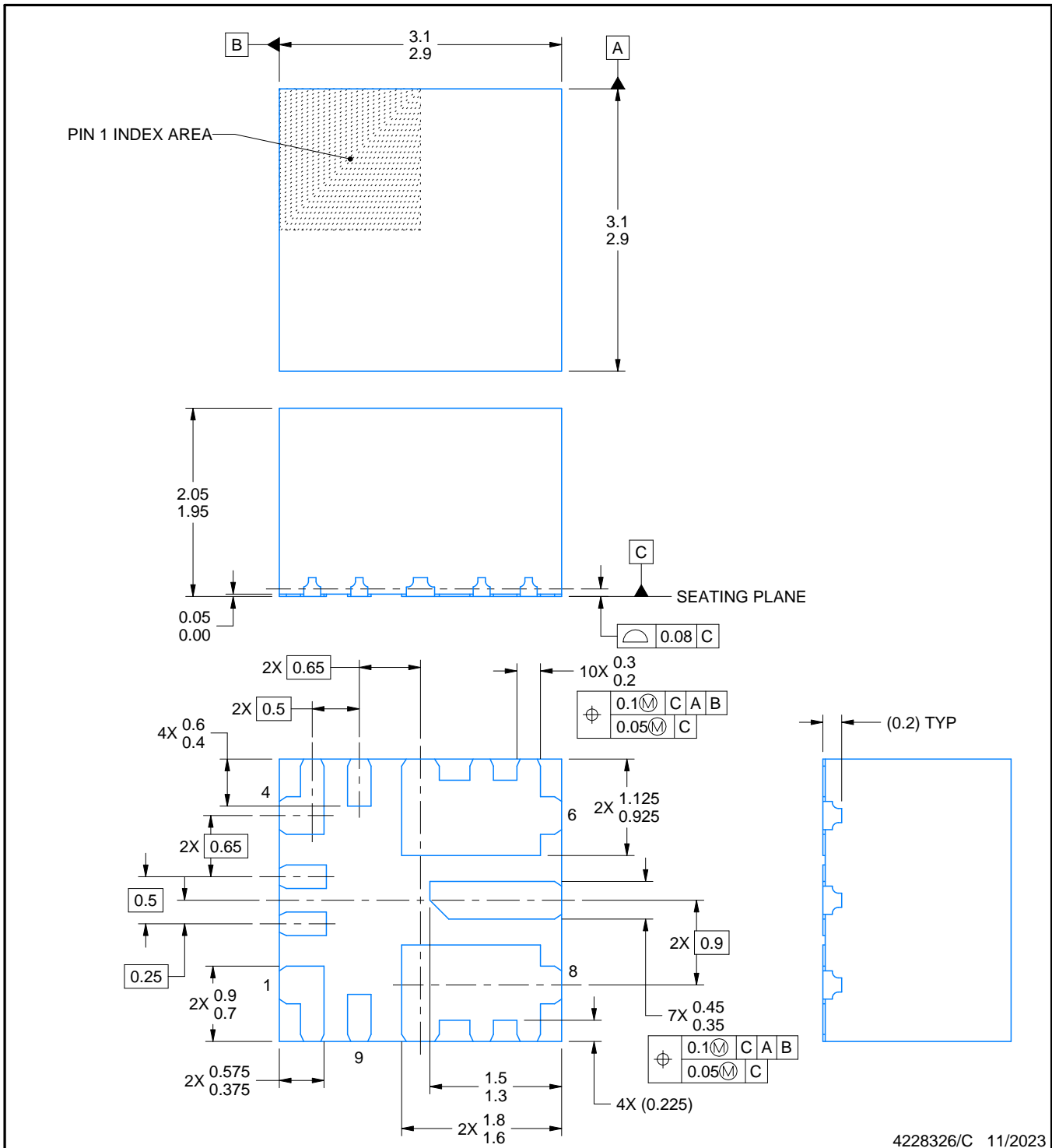


# PACKAGE OUTLINE

RDS0009A

QFN-FCMOD - 2.05 mm max height

QUAD FLATPACK - NO LEAD



NOTES:

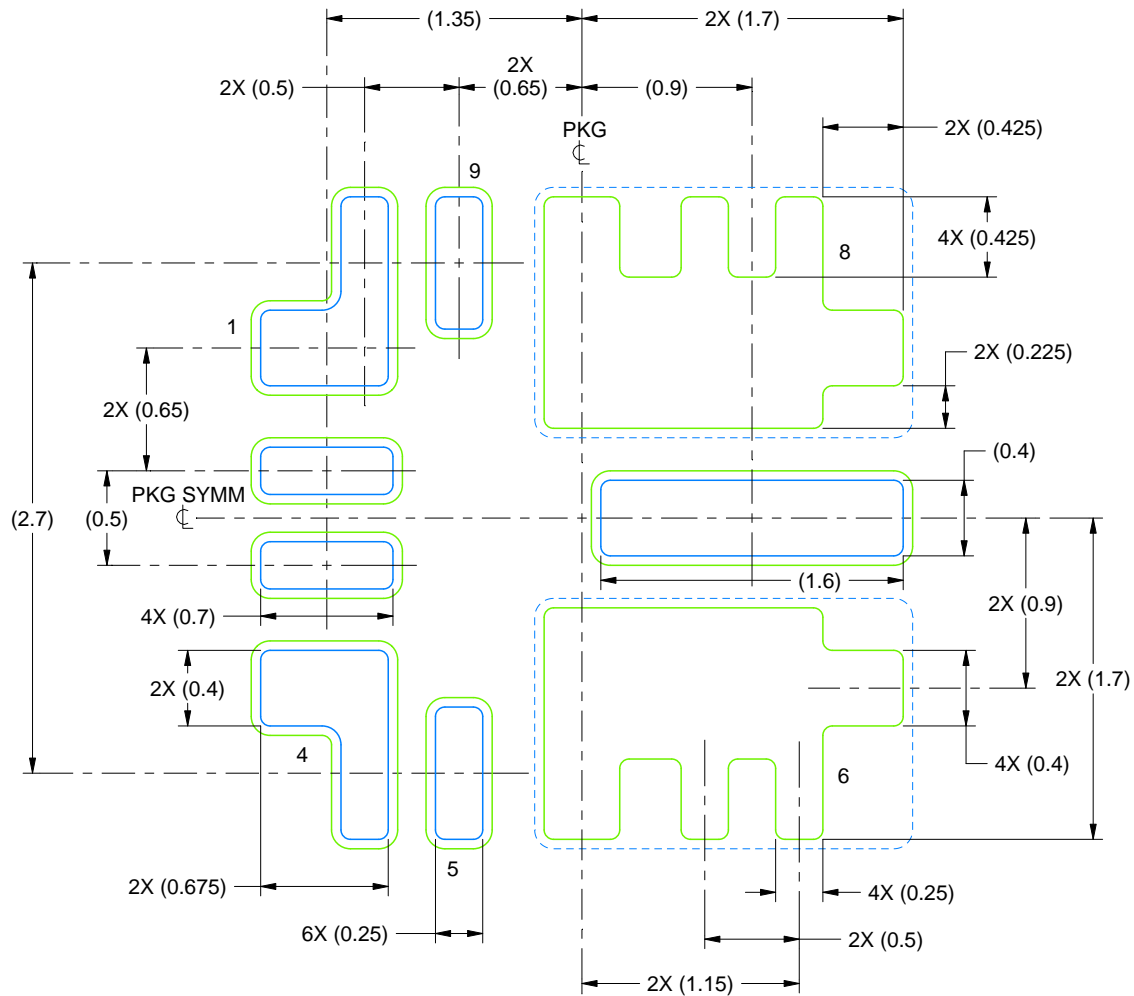
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

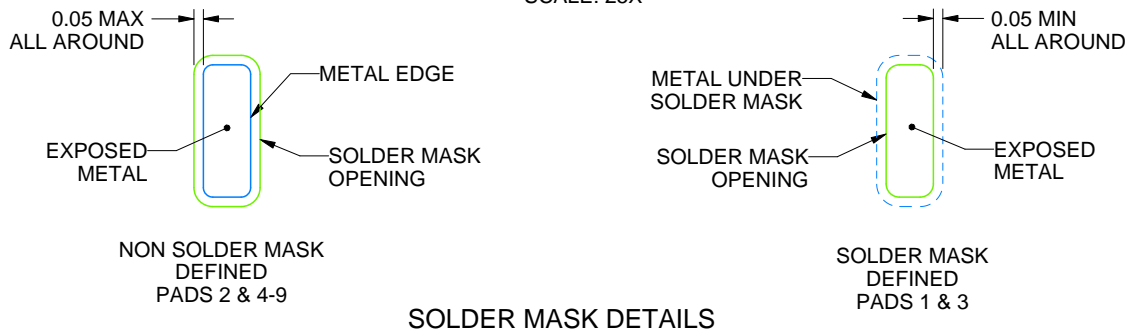
RDS0009A

QFN-FCMOD - 2.05 mm max height

QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
SCALE: 25X



SOLDER MASK DETAILS

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NOTES: (continued)

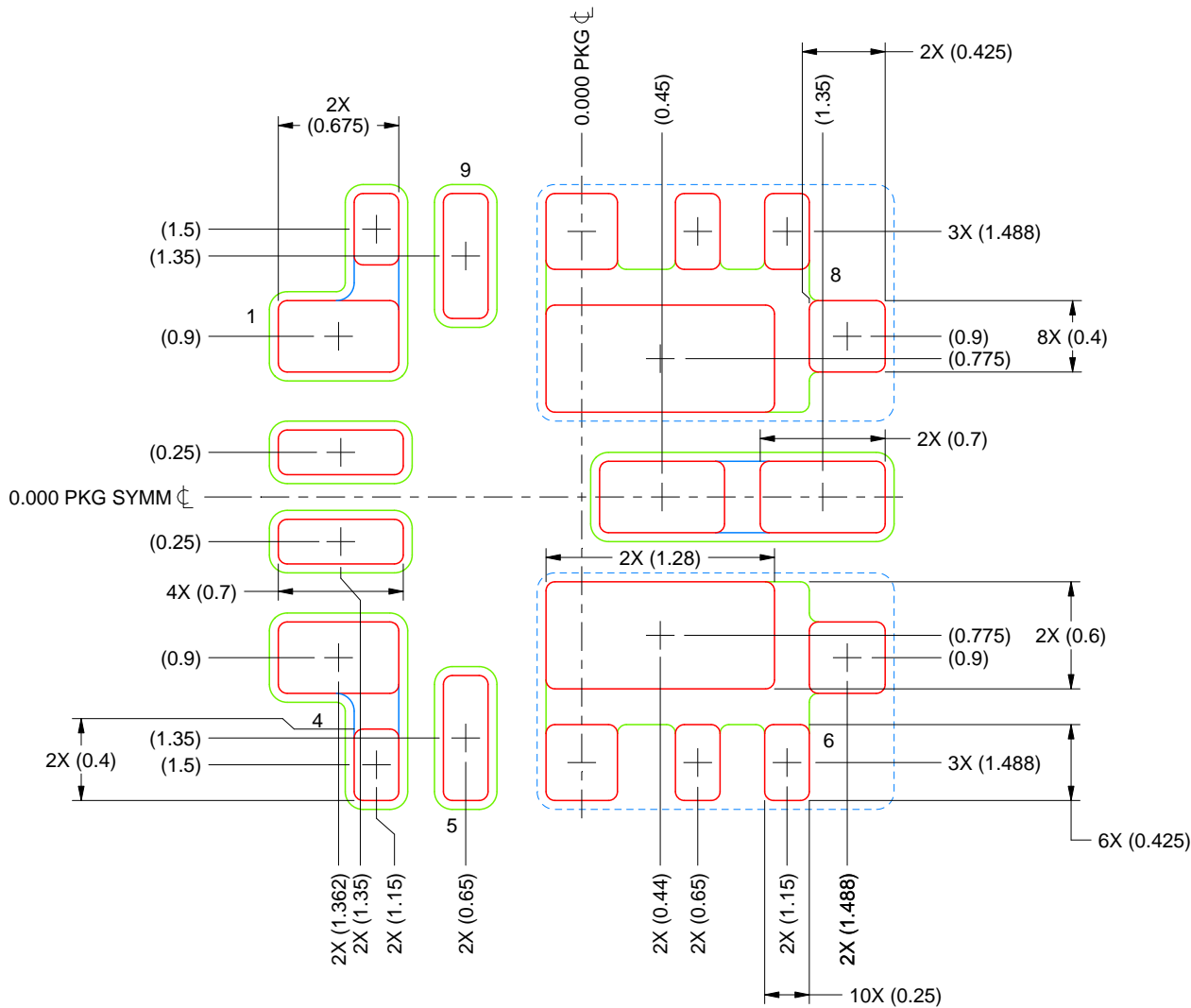
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RDS0009A

QFN-FCMOD - 2.05 mm max height

QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL  
 SCALE: 25X

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
 PADS 1 & 3: 76%  
 PADS 2, 5 & 8: 88%

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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